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(54) **PACKAGE OF ENVIRONMENTALLY SENSITIVE ELECTRONIC DEVICE AND FABRICATING METHOD THEREOF**

(71) Applicant: **INDUSTRIAL TECHNOLOGY RESEARCH INSTITUTE**, Hsinchu (TW)

(72) Inventor: **Kuang-Jung Chen**, Zhubei (TW)

(73) Assignee: **INDUSTRIAL TECHNOLOGY RESEARCH INSTITUTE**, Hsinchu (TW)

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CPC ***H05K 3/284*** (2013.01); ***H05K 1/189*** (2013.01); *H05K 2201/10128* (2013.01); *H05K 2201/10136* (2013.01); *Y10T 29/49126* (2015.01)

(58) **Field of Classification Search**
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See application file for complete search history.

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Primary Examiner — William H Mayo, III
Assistant Examiner — Hiram E Gonzalez
(74) *Attorney, Agent, or Firm* — Locke Lord LLP; Tim Tingkang Xia, Esq.

(57) **ABSTRACT**

A package of an environmentally sensitive electronic device and a fabricating method thereof are provided, wherein the package may include a first substrate, a second substrate, the environmentally sensitive electronic device, a packaging body, and a filler. In one or more embodiments, the environmentally sensitive electronic device may be disposed on the first substrate and located between the first substrate and the second substrate. The filler is disposed between the first substrate and the second substrate and covers the environmentally sensitive electronic device. The packaging body is sandwiched between the first substrate and the second substrate and encloses the environmentally sensitive electronic device and the filler. A material for the packaging
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